Specification of Thermoelectric Module

TEHC1-19914L

Description

The 199 couples, 50 mm \times 50 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 °C, designed for superior cooling and heating up to 100°C or 200°C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Performance Specification Sheet

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	26.3	28.3	Voltage applied to the module at DT _{max}
I _{max(} amps)	14.2	14.2	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	237.6	259.4	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	1.4	1.6	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters

Cold side: Te Hot side: Th

Manufacturing Options

A. Solder:	B. Sealant:
1. T100: BiSn (Tmelt=138°C)	1. NS: No sealing (Standard)
2. T200: CuAgSn (Tmelt = 217°C)	2. SS: Silicone sealant
3. T240: SbSn (Tmelt = 240°C)	3. EPS: Epoxy sealant
C. Ceramics:	D. Ceramics Surface Options:
1. Alumina (Al ₂ O ₃ , white 96%)	1. Blank ceramics (not metalized)

2. Metalized

Naming for the Module

2. Aluminum Nitride (AlN)

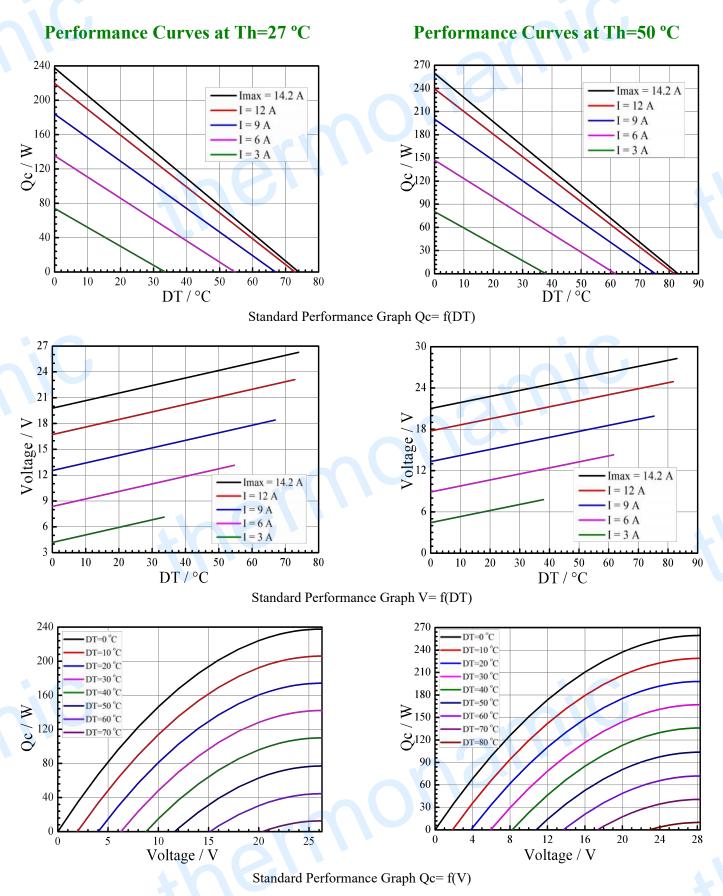
Ordering Option

Thickness Flatness/ Lead wire length(mm) TEHC1-19914L-X-X-X-X Suffix Standard/Optional length (mm) Parallelism (mm) Ceramics Flatness/ Parallelism TF $0:3.4 \pm 0.1$ 0: 0.1/0.1150±3/Specify Sealant Solder TF $1{:}3.4\pm0.05$ 1:0.05/0.05 150±3/Specify TEHC1-19914L-T100 -NS -TF00 -AlO T100: BiSn(Tmelt=138°C) Eg. TF00: Thickness 3.4 ± 0.1 (mm) and Flatness 0.1/0.1 (mm) NS: No sealing AlO: Alumina (Al2O3, white 96%)

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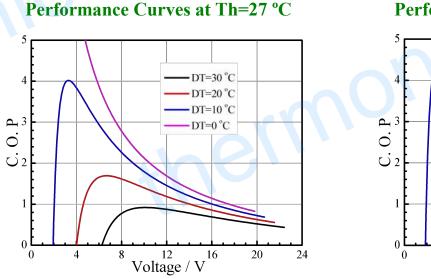
TEHC1-19914L



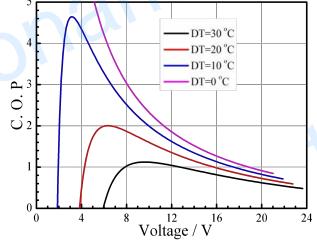
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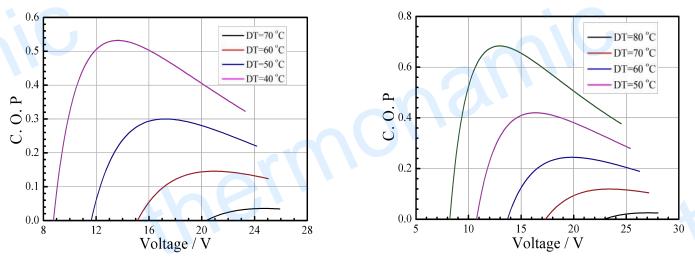
TEHC1-19914L



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 70/80 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- \bullet Operation below $I_{max} \text{ or } V_{max}$
- Work under DC

Note: All specifications subject to change without notice.